

Reference Schematics For RK3528

RK3528_BOX_REF_SCH_V10

Main Functions Introduction

- 1) Power: DiscretePower:BUCK+LDO or PMIC RK805-6
- 2) RAM: DDR3 4x16bit
DDR4 2x16Bit
DDR4 4x16Bit
LPDDR3 1x32bit
LPDDR4/LPDDR4X 1x32bit
- 3) ROM: eMMC5.1 or FSPI Flash
- 4) Support: Micro SD Card3.0
- 5) Support: 1 x USB3.0 OTG + 1 x USB2.0 HOST
- 6) Support: 1 x HDMI2.0 TX
- 7) Support: 1 x AV OUT
- 8) Support: SDIO WiFi5 + UART/PCM BT
PCIE WIFI5 + UART/PCM BT
- 9) Support: 1 x Ethernet(Embed PHY) + 1x Ethernet(RGMII or RMII)
- 10) Support: Optical S/PDIF TX
- 11) Support: IR Receiver
- 12) Support: Audio-MicArray 2xI2S-DMIC or 4xPDM-DMIC
- 13) Support: RECOVER/RESET/SARADC_BOOT_KEY,HW_ID
- 14) Support: 1 x PCIE2.0 Slot
- 15) Support: Debug UART

HINLINK


Project:	RK3528_HT2	 HINLINK
File:	00.Cover Page	
Date:	Friday, December 08, 2023	Rev: <Revision>
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Generate Bill of Materials

Header:

Item\tPart\tDescription\tPCB Footprint\tReference\tQuantity\tOption

Combined property string:

{Item}\t{Value}\t{Description}\t{PCB Footprint}\t{Reference}\t{Quantity}\t{Option}

Description


Note

Option

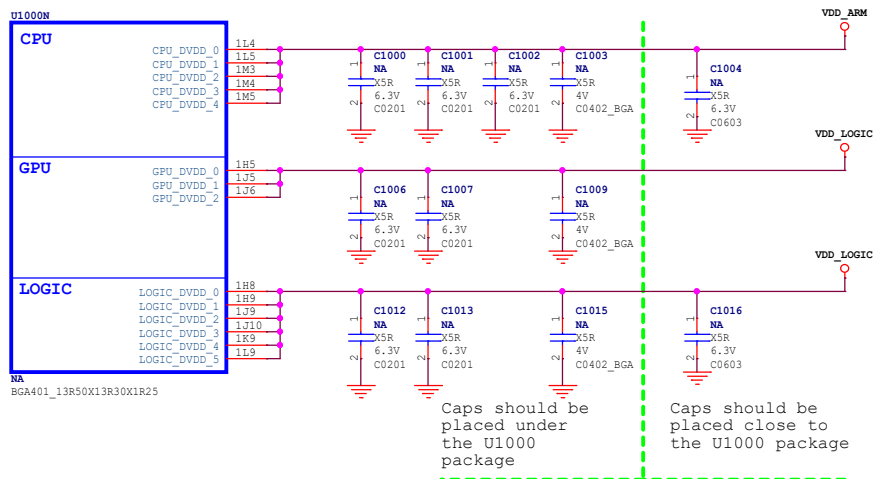
Notes

- NOTE 1:
Component parameter description
1. DNP stands for component not mounted temporarily
2. If Value or option is DNP, which means the area is reserved without being mounted
- NOTE 2:
Please use our recommended components to avoid too many changes.
For more informations about the second source,please refer to our AVL.

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File:	01.Index and Notes		
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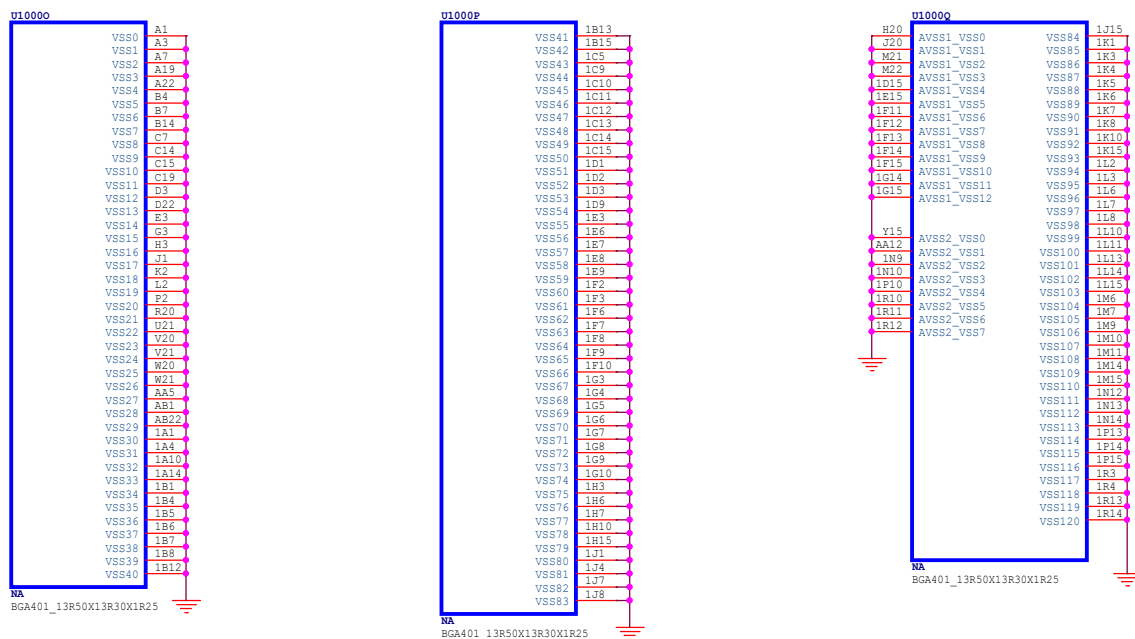
RK3528 N (POWER)




Note:

Caps of between dashed green lines and U1000
should be placed under the U1000 package.
Other caps should be placed close to the U1000 package

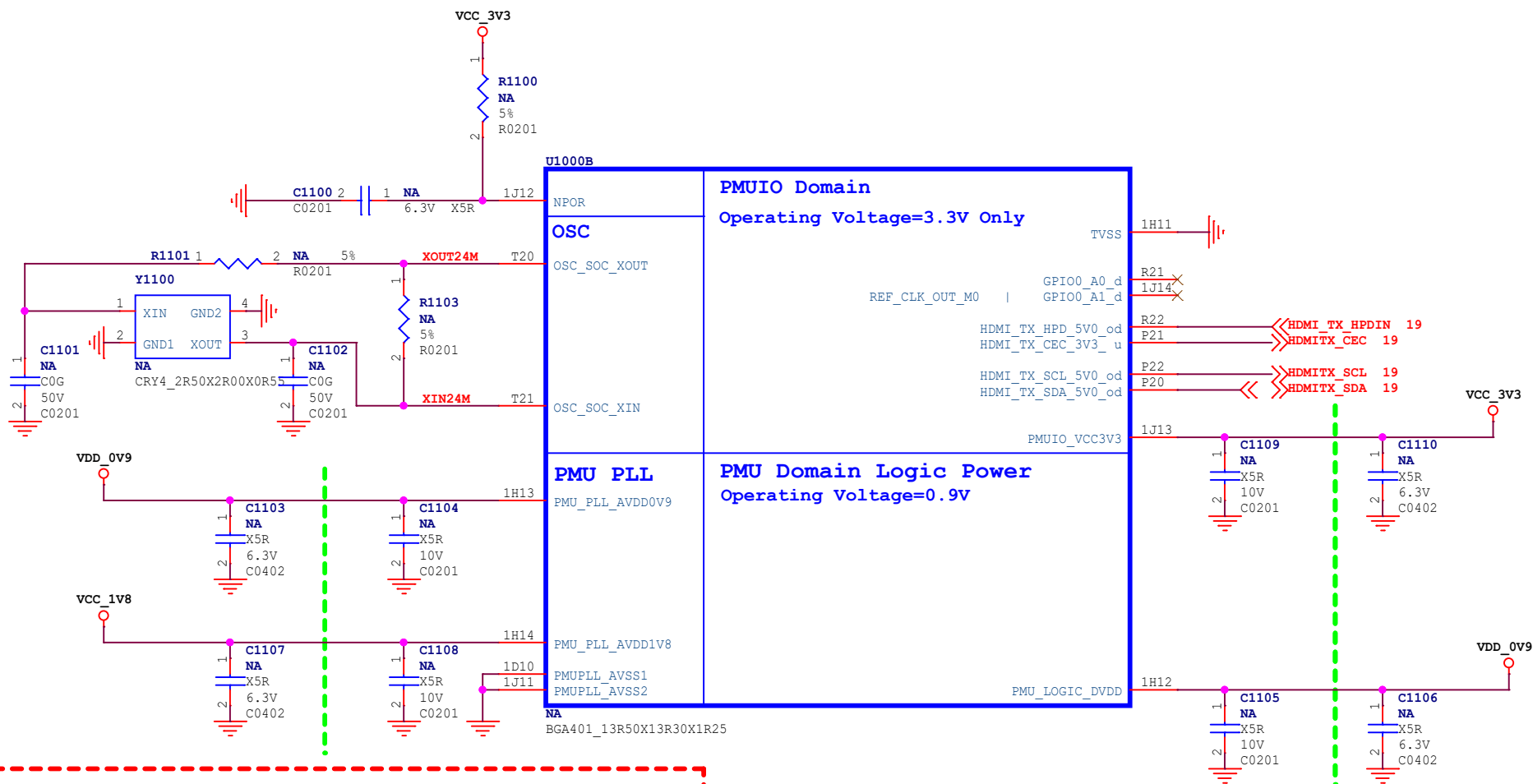
RK3528 O/P/Q (GND)



HINLINK

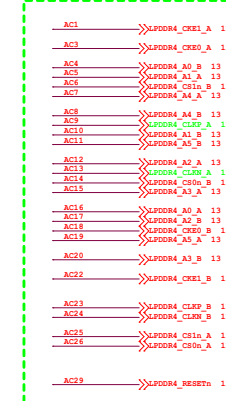
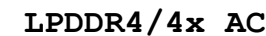
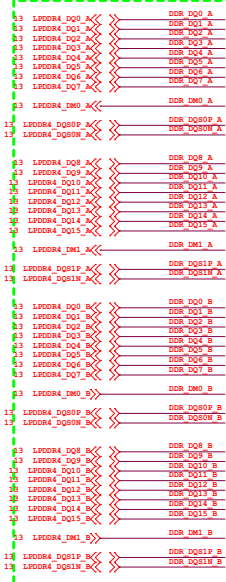
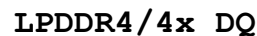
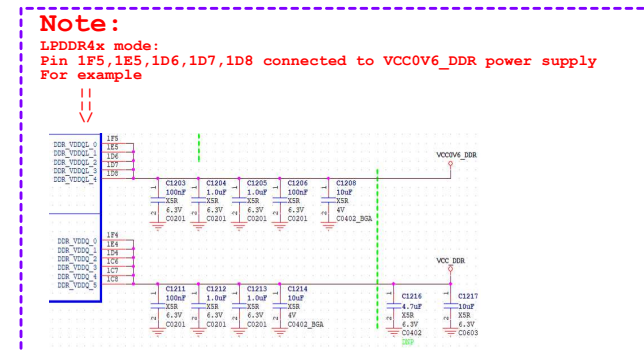
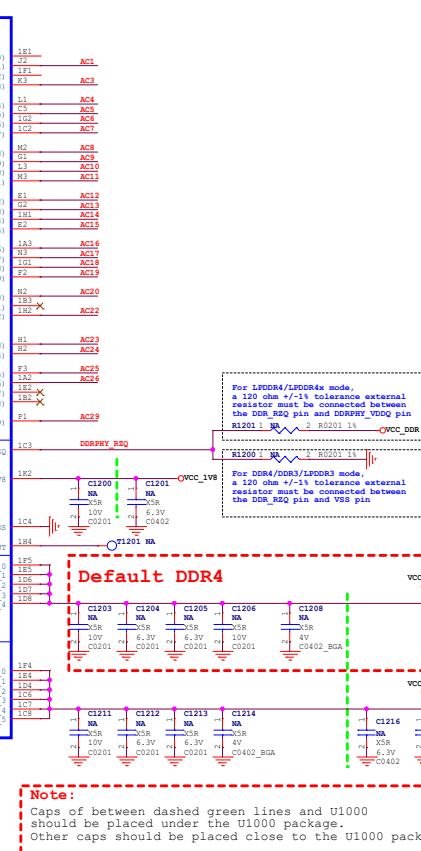
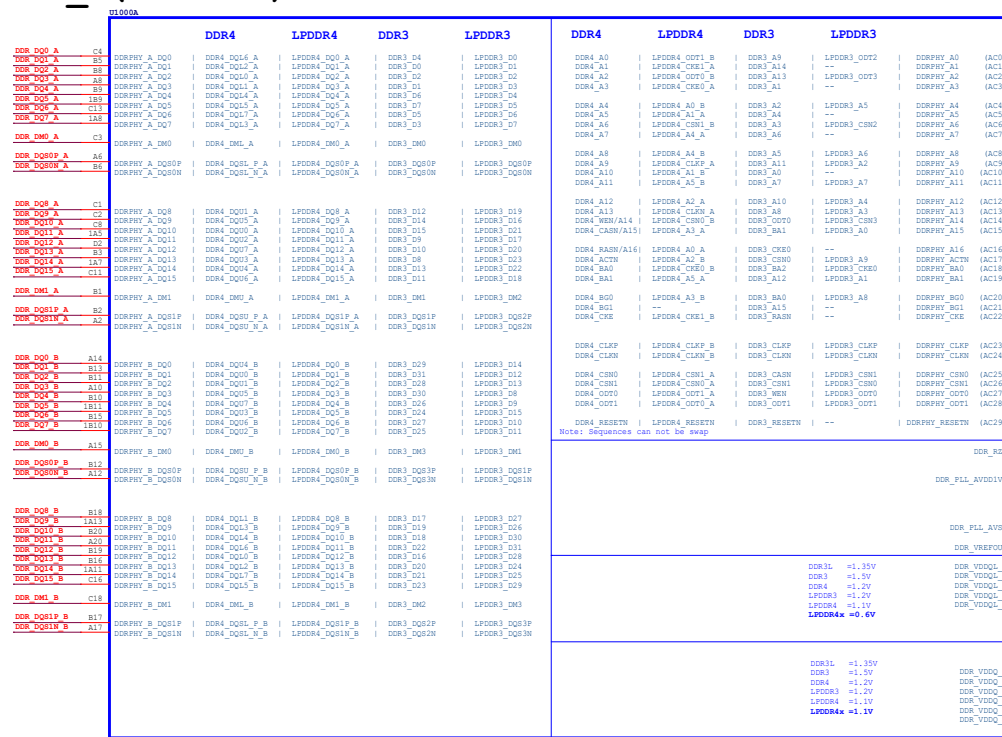
Project:	RK3528_HT2	 HINLINIK
File:	02.RK3528 Power/GND	
Date:	Monday, January 29, 2024	Rev: <Revision>
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RK3528_B (OSC/PLL/PMUIO Domain)

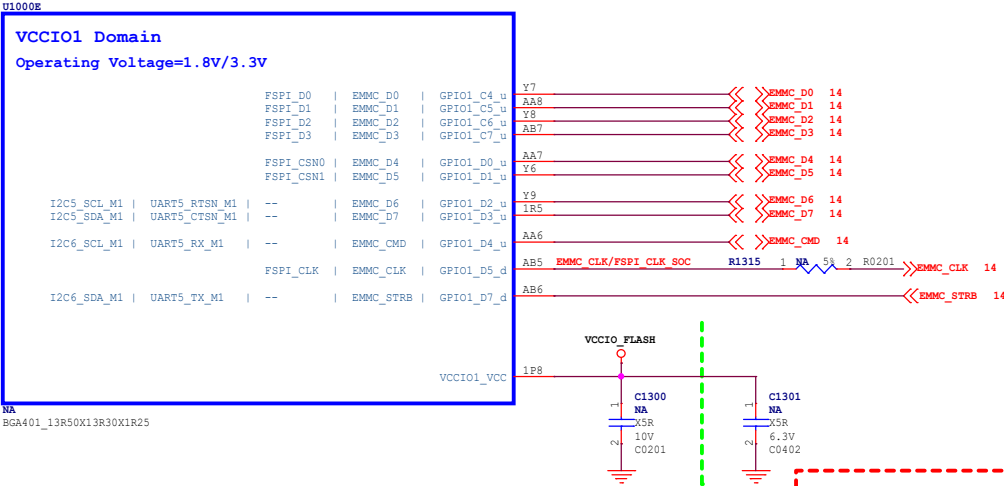


Note:
Caps of between dashed green lines and U1000
should be placed under the U1000 package.
Other caps should be placed close to the U1000 package

RK3528 A (DDR PHY)



RK3528_E (VCCIO1 Domain)

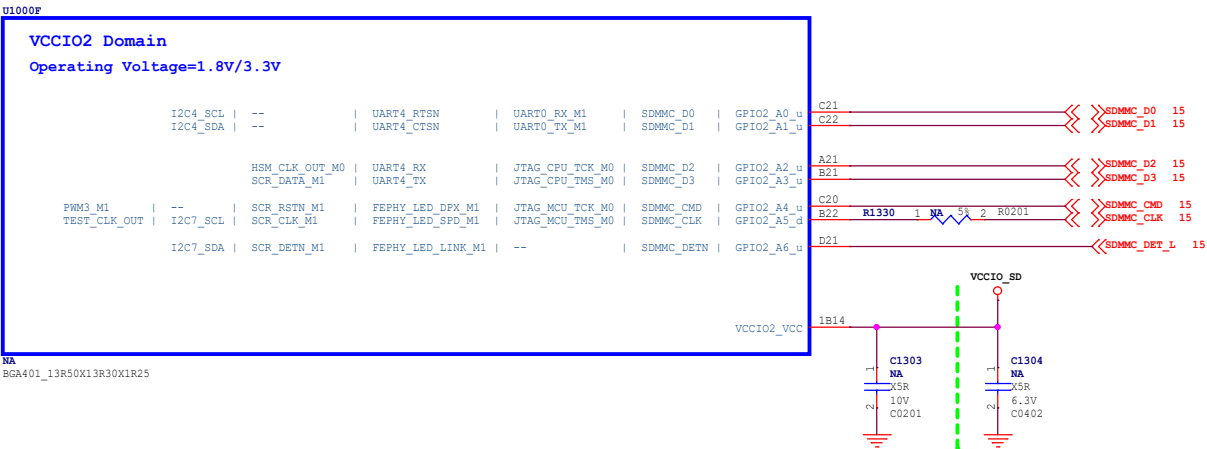


FSPI(Flexible Serial Peripheral Interface) is only used to connect SPI Flash/Memory devices.
Do not use for connecting to other SPI devices

Default
DiscretePower solution, power by VCC_1V8
PMIC solution, power by VCC1V8_EMMC,only 1.8V

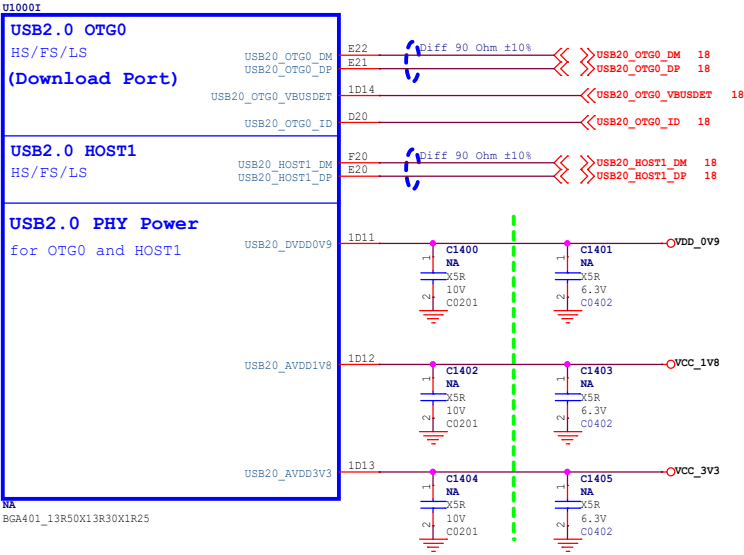
Note:
Caps of between dashed green lines and U1000
should be placed under the U1000 package.
Other caps should be placed close to the U1000 package

RK3528_F (VCCIO2 Domain)



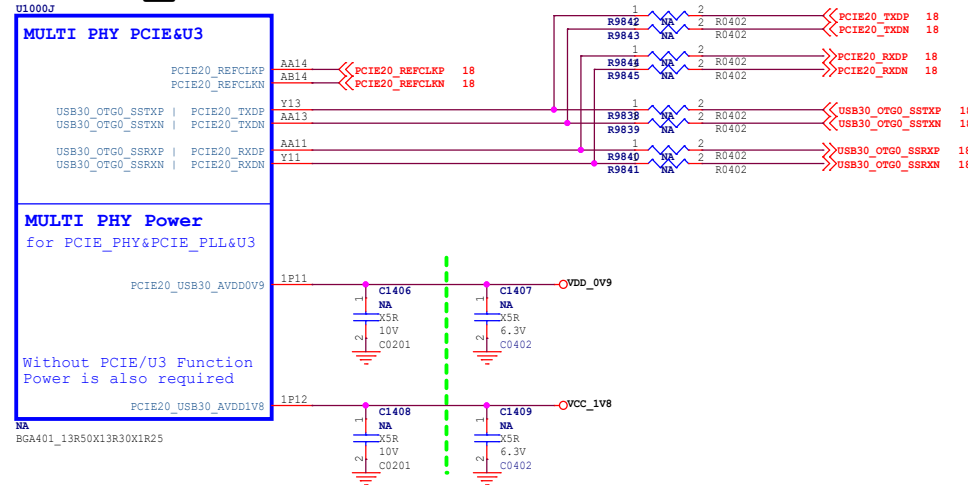
Note:
Caps of between dashed green lines and U1000
should be placed under the U1000 package.
Other caps should be placed close to the U1000 package

RK3528_I (USB2.0 OTG/HOST)



Note:
Caps of between dashed green lines and U1000 should be placed under the U1000 package.
Other caps should be placed close to the U1000 package

RK3528_J (PCIE2.0/U3 PHY)

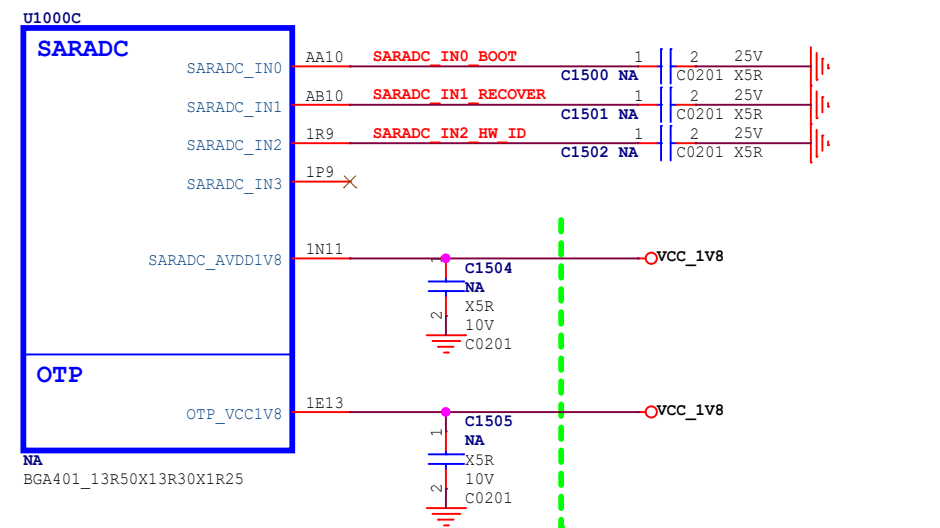


Note:
Caps of between dashed green lines and U1000 should be placed under the U1000 package.
Other caps should be placed close to the U1000 package

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Project:	RK3528_HT2	Rev:	<Revision>
File:	06.RK3528 USB/PCIE Controller	Sheet:	7 of 23
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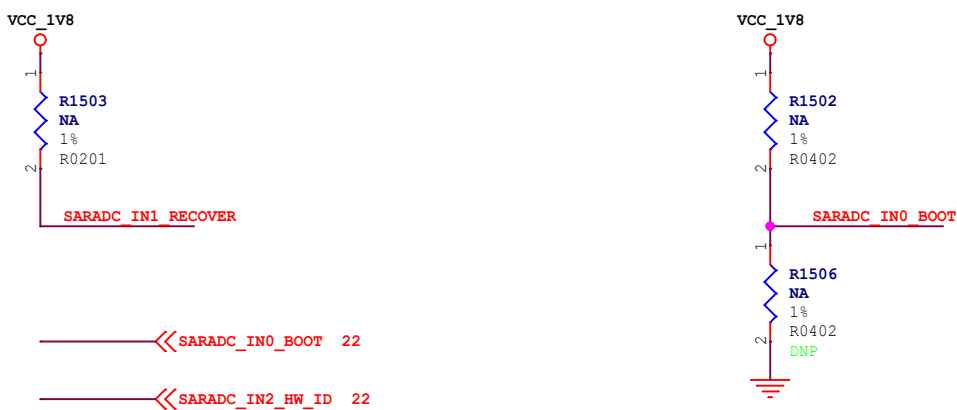
RK3528_C (Saradc/OTP)



Note:

Caps of between dashed green lines and U1000 should be placed under the U1000 package.

Other caps should be placed close to the U1000 package



TABLE

Item	Rup	Rdown	ADC	BOOT MODE
LEVEL1	DNP	100K	0	USB (Maskrom mode)
LEVEL2	100K	12K	114	
LEVEL3	100K	27K	228	FSPI--USB
LEVEL4	100K	51K	342	
LEVEL5	100K	82K	456	
LEVEL6	100K	120K	570	EMMC--USB
LEVEL7	100K	200K	683	EMMC--SD Card--USB
LEVEL8	100K	330K	796	SD Card--USB
LEVEL9	100K	820K	910	
LEVEL10	100K	DNP	1023	FSPI--EMMC--SD Card--USB


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Project: RK3528_HT2

File: 07.RK3528 SARADC/OTP

Date: Monday, January 29, 2024

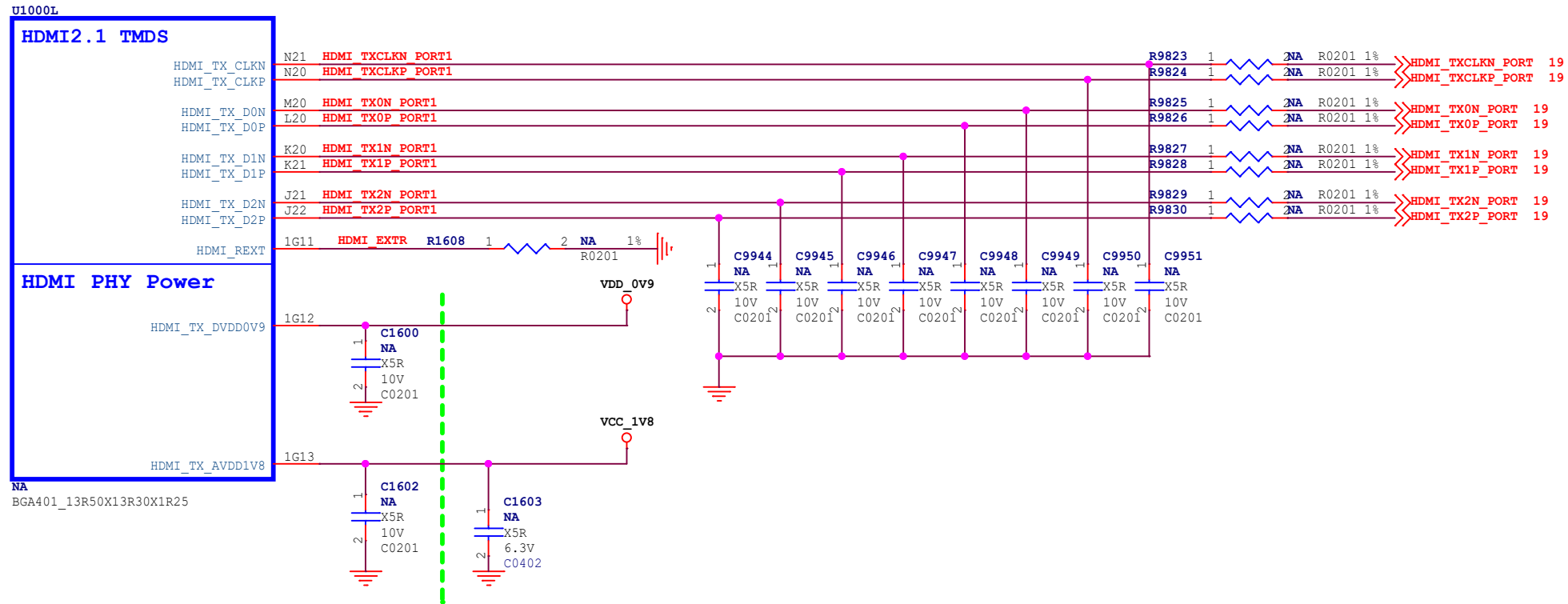
Designer: <designer>

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Rev: <Revision>

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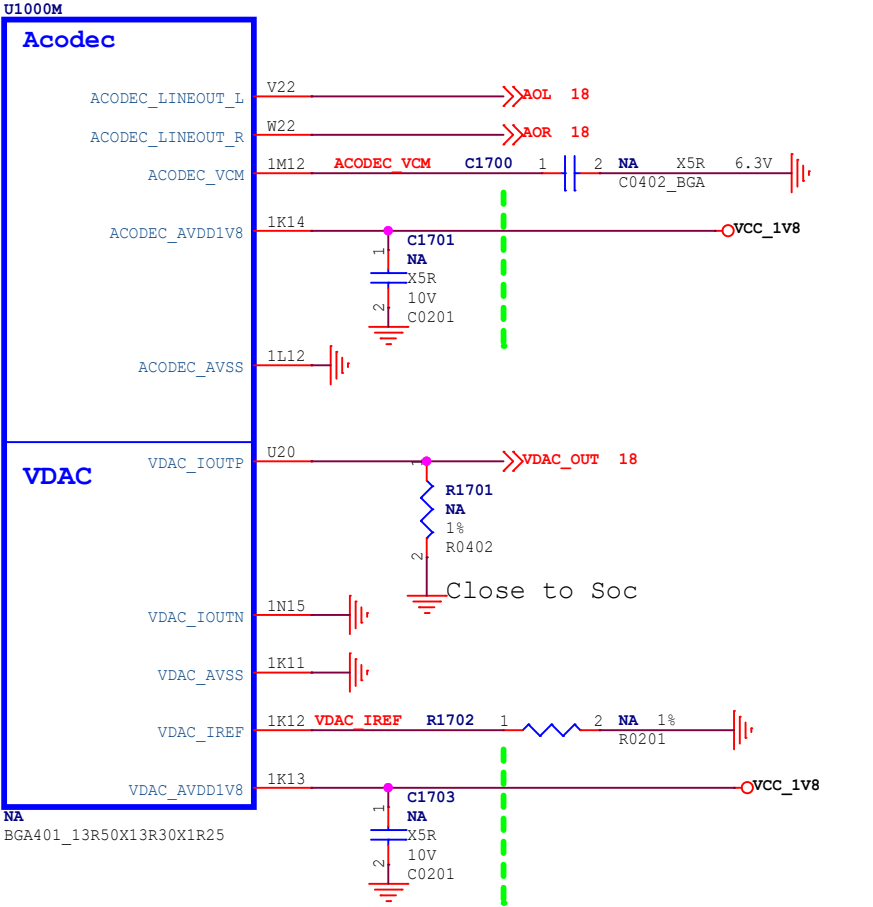
RK3528_L (HDMI PHY)



Note:

Caps of between dashed green lines and U1000 should be placed under the U1000 package.
Other caps should be placed close to the U1000 package


RK3528_M (Acodec/VDAC)



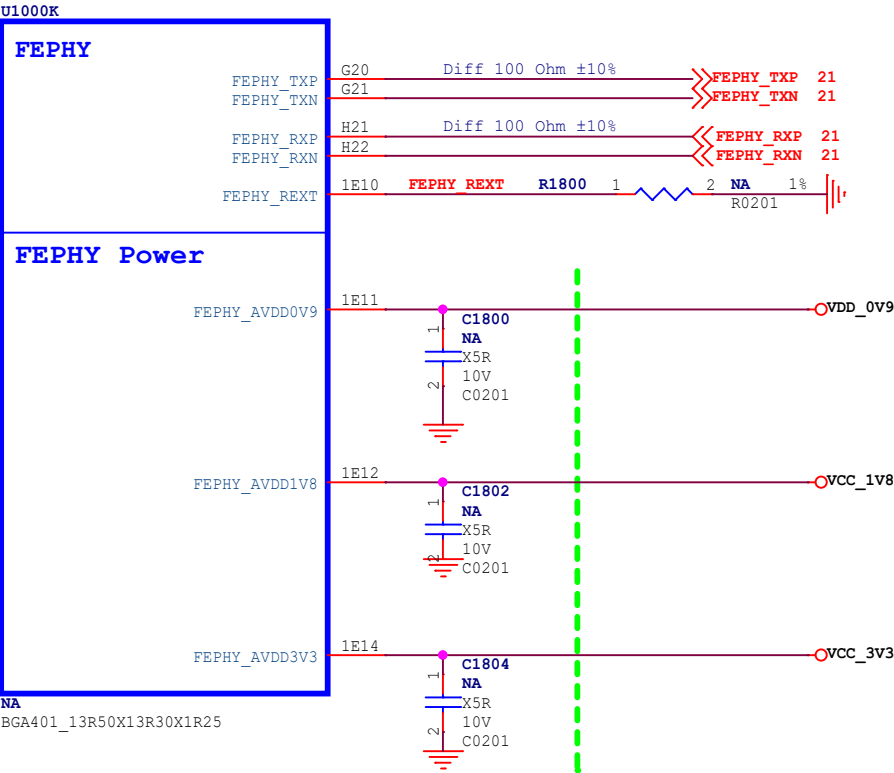
Note:

Caps of between dashed green lines and U1000 should be placed under the U1000 package.

Other caps should be placed close to the U1000 package


HINLINK			
Project:	RK3528_HT2	 HINLINK	
File:	09.RK3528 AV OUT		
Date:	Monday, January 29, 2024	Rev:	<Revision>
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RK3528_K (Embed FEPHY)

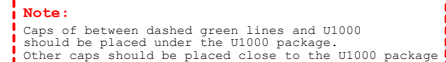
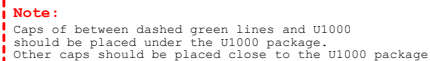


Note:

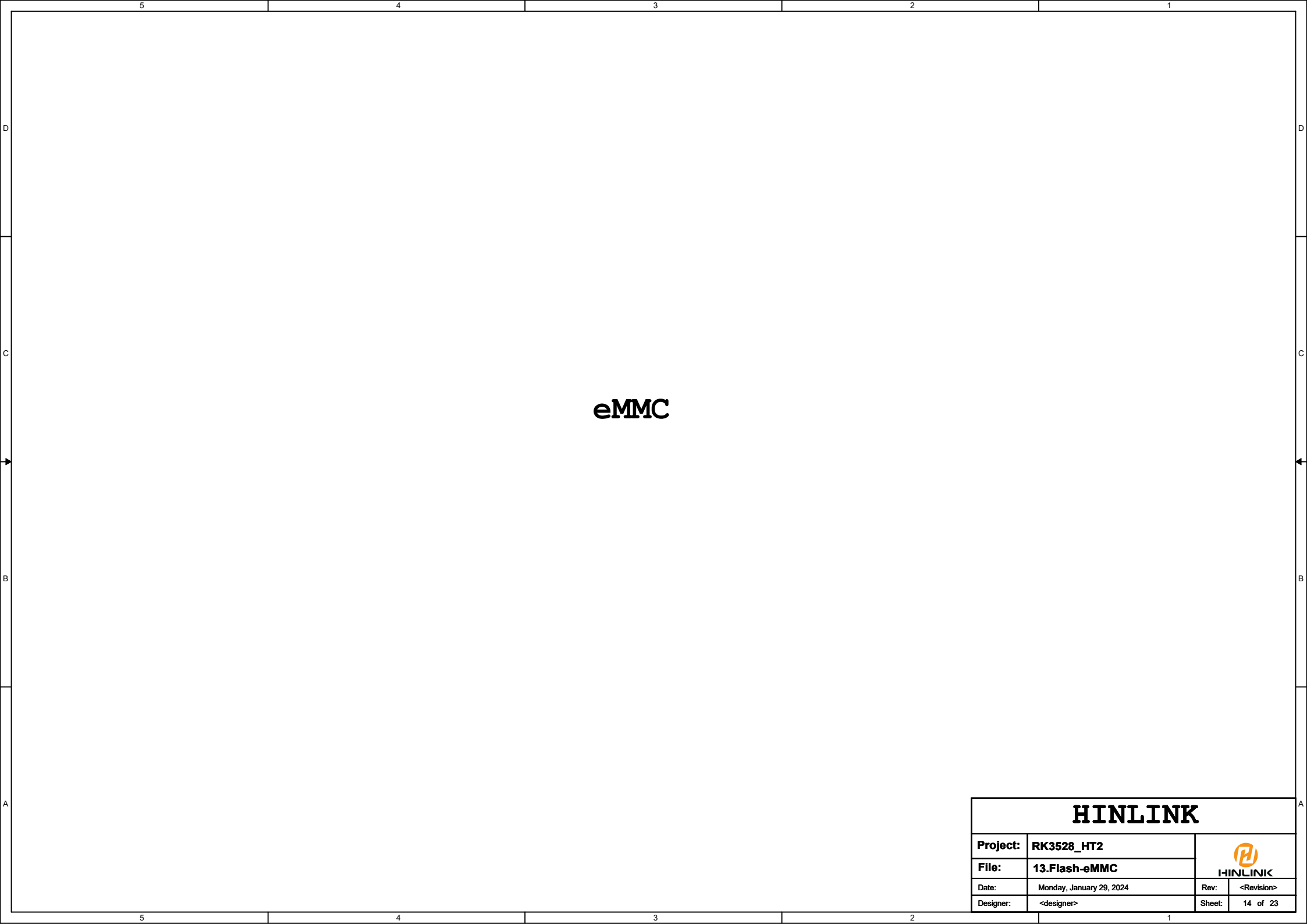
Caps of between dashed green lines and U1000 should be placed under the U1000 package.
Other caps should be placed close to the U1000 package


HINLINK			
Project:	RK3528_HT2	 HINLINK	
File:	10.RK3528 Embed FEPHY		
Date:	Monday, January 29, 2024	Rev:	<Revision>
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RK3528 G (VCCIO3 Domain)

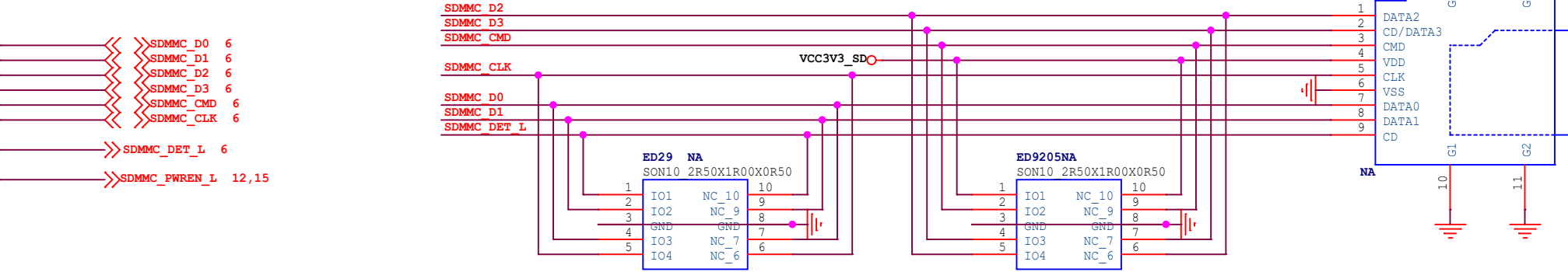


Note:
Caps of between dashed green lines and U1000
should be placed under the U1000 package.
Other caps should be placed close to the U1000 package

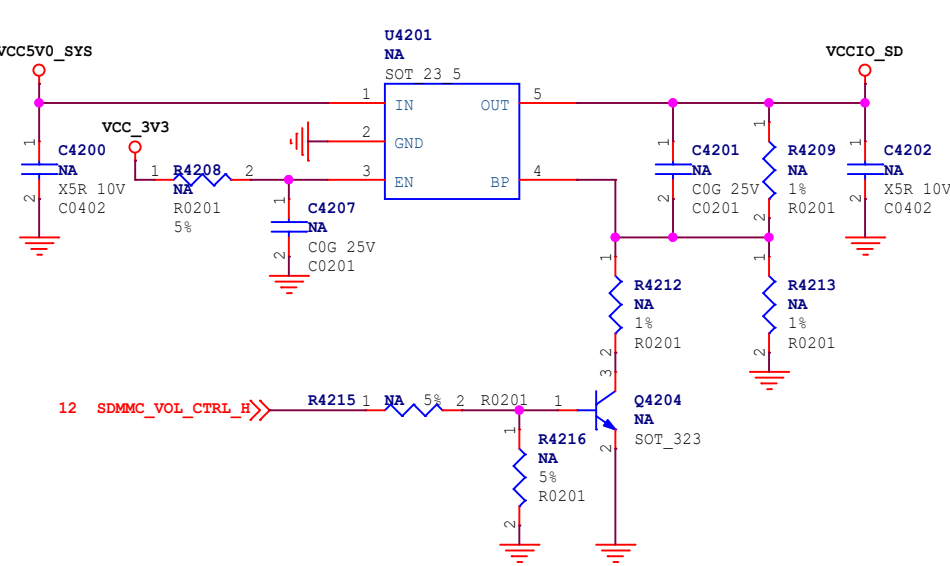


HINLINK			
Project:	RK3528_HT2	 HINLINK	
File:	13.Flash-eMMC		
Date:	Monday, January 29, 2024	Rev:	<Revision>
Designer:	<designer>	Sheet:	14 of 23

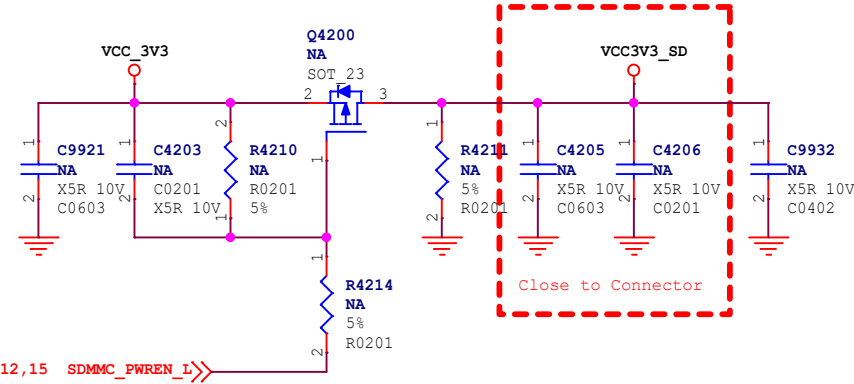
TF Card



VCCIO_SD




VCC3V3_SD

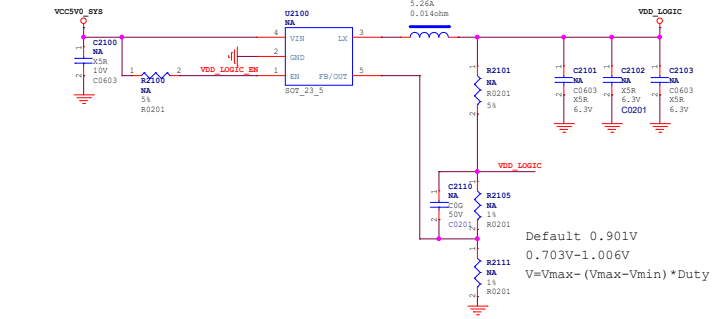


SDMMC_PWREN=L VCC_SD=3.3V(Default)
SDMMC_PWREN=H VCC_SD=0V

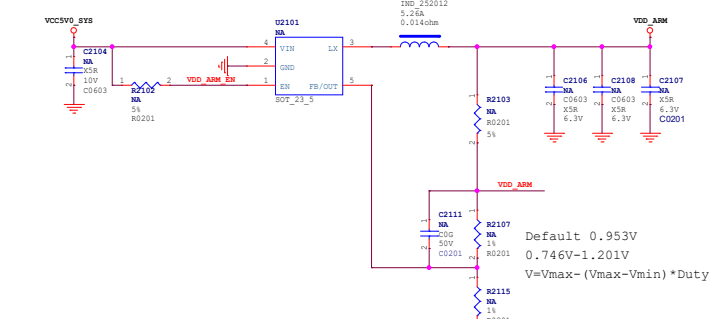
SDIO2.0 SDMMC0_VOL_CTRL=H VCCIO_SD=3.34V(Default)
SDIO3.0 SDMMC0_VOL_CTRL=L VCCIO_SD=1.816V

HINLINK			
Project:	RK3528_HT2	 HINLINK	
File:	14.Flash-Micro-SD Card		
Date:	Monday, January 29, 2024	Rev:	<Revision>
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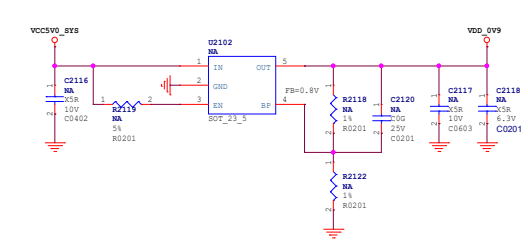
VCC5V0_SYS-->VDD_LOGIC
Step 1



VCC5V0_SYS-->VDD_ARM
Step 1

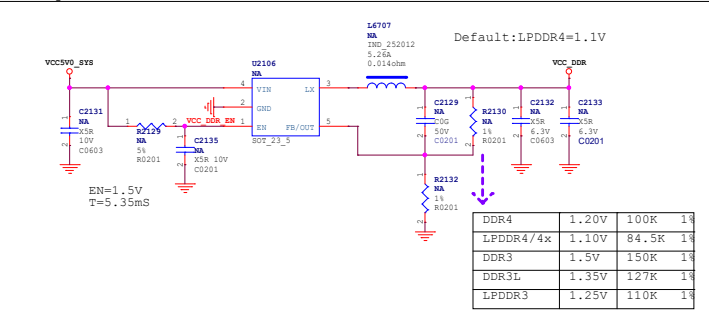


VCC5V0_SYS-->VDD_0V9
Step 1

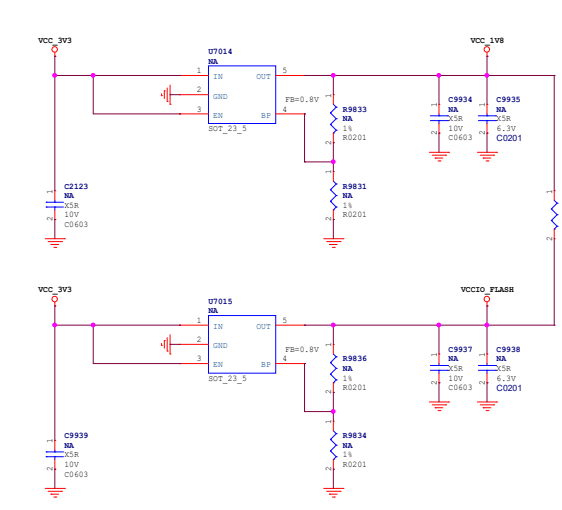


Note:
When LAYOUT, a star must be used,
Branch to each load

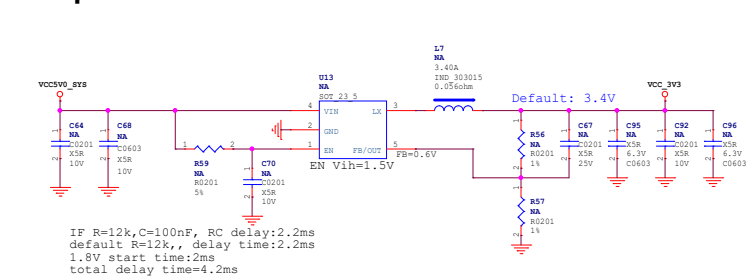
VCC5V0_SYS-->VCC_DDR
Step 2



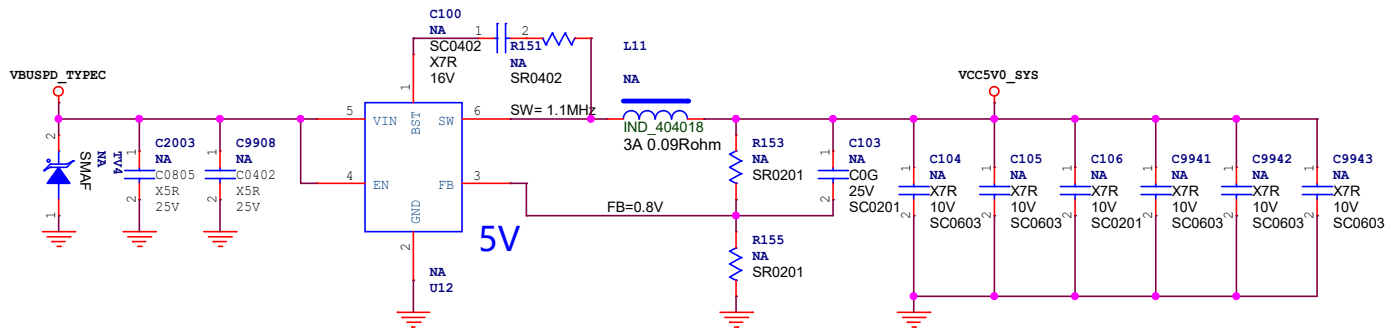
VCC_3V3->VCC_1V8(LDO)
Step 2



VCC5V0_SYS-->VCC_3V3
Step 2




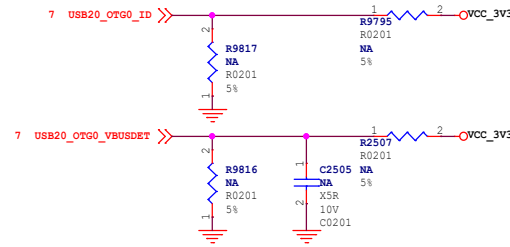
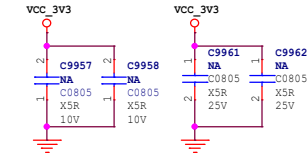
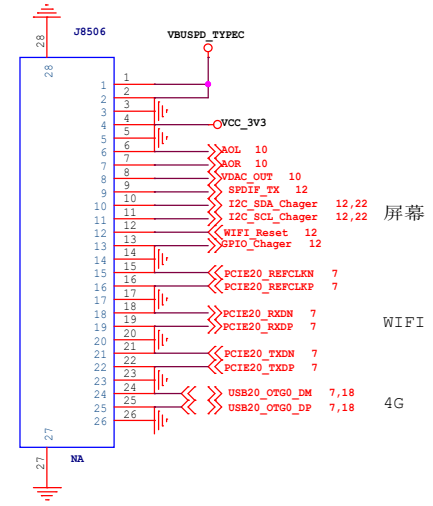
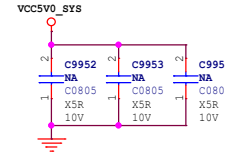
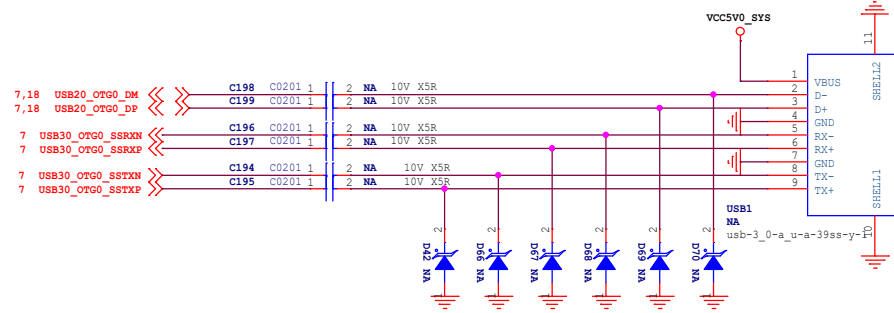
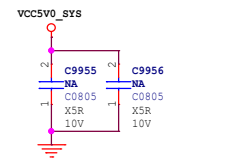
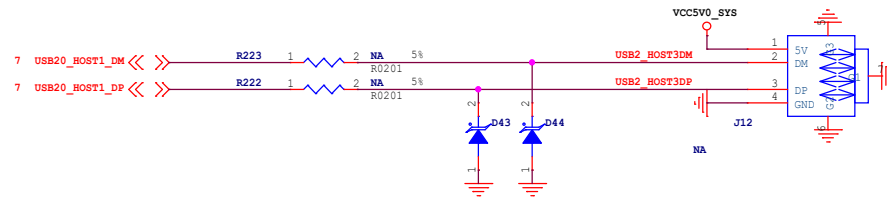
5V_SYS




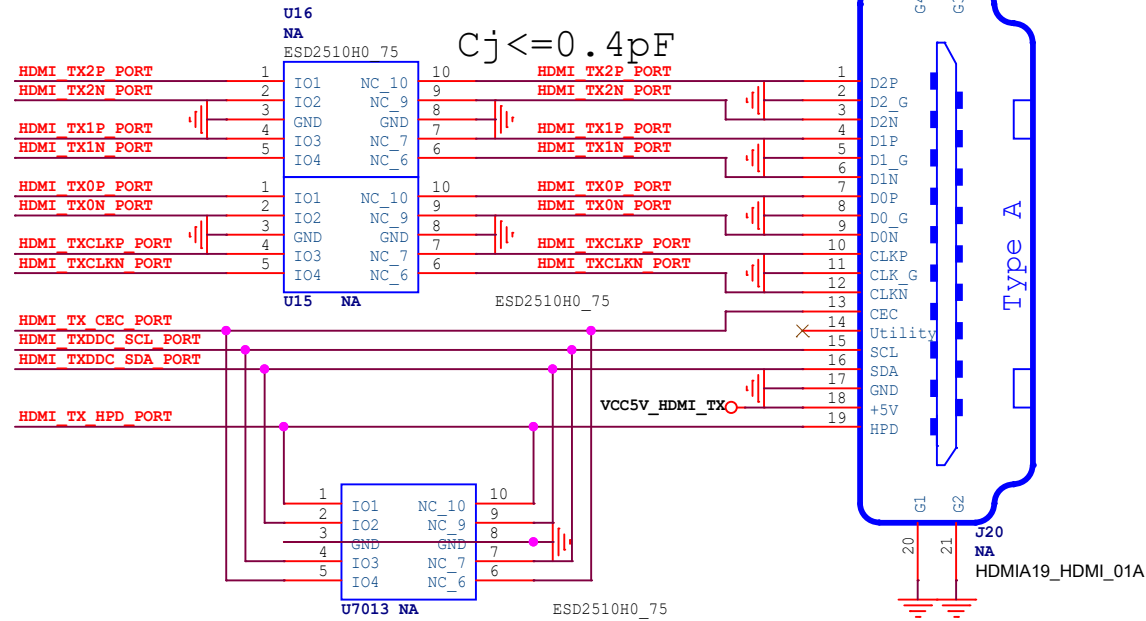
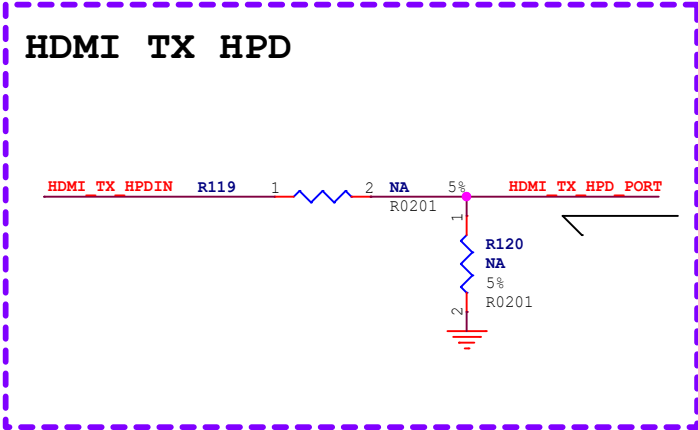
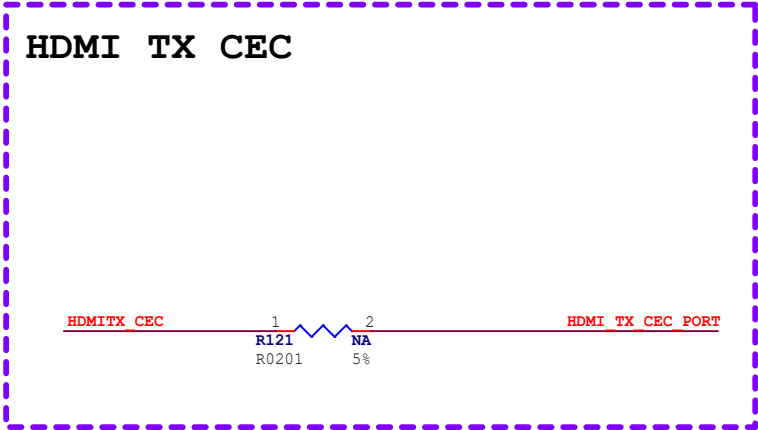
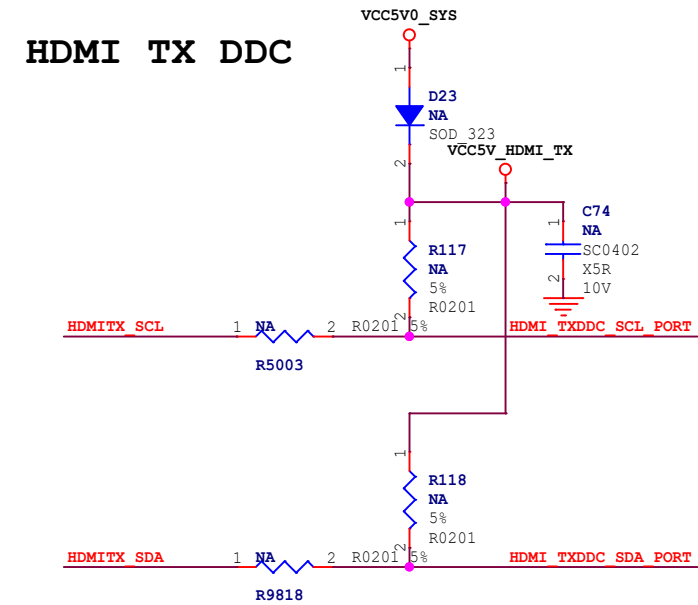
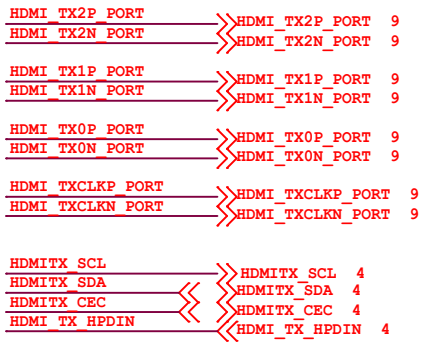
USB+Debug

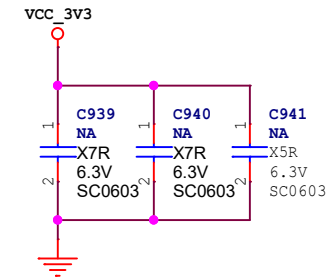
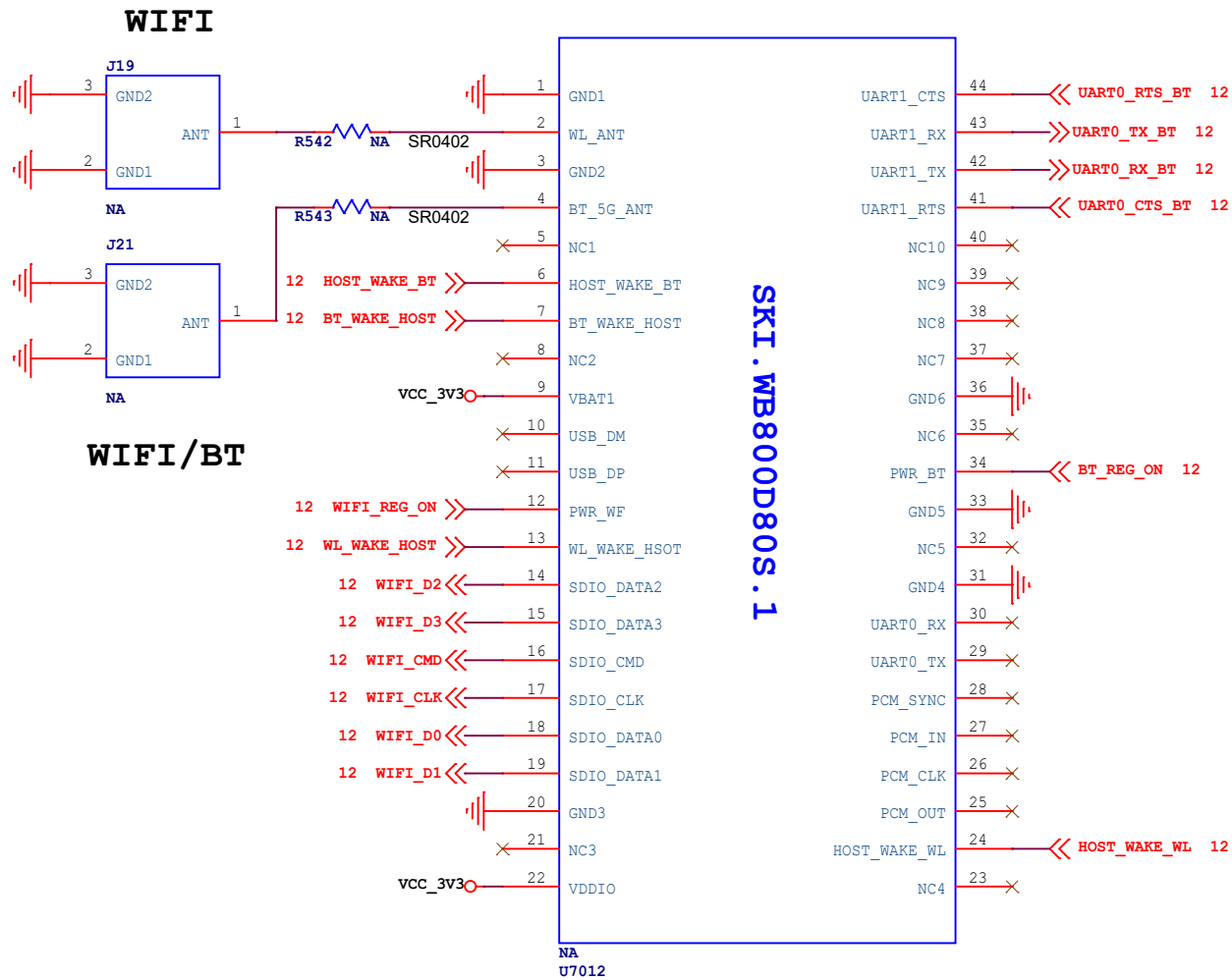
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Project:	RK3528_HT2		
File:	16.Power-DCIN		
Date:	Monday, January 29, 2024	Rev:	<Revision>
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HINLINK			
Project:	RK3528_HT2		 HINLINK
File:	17.USB3.0+2.0 Port		
Date:	Monday, January 29, 2024		
Designer:	<designer>		
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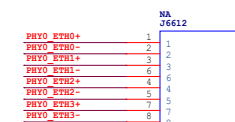
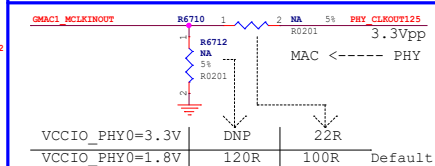
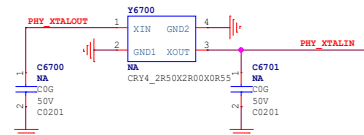
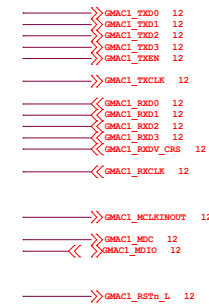




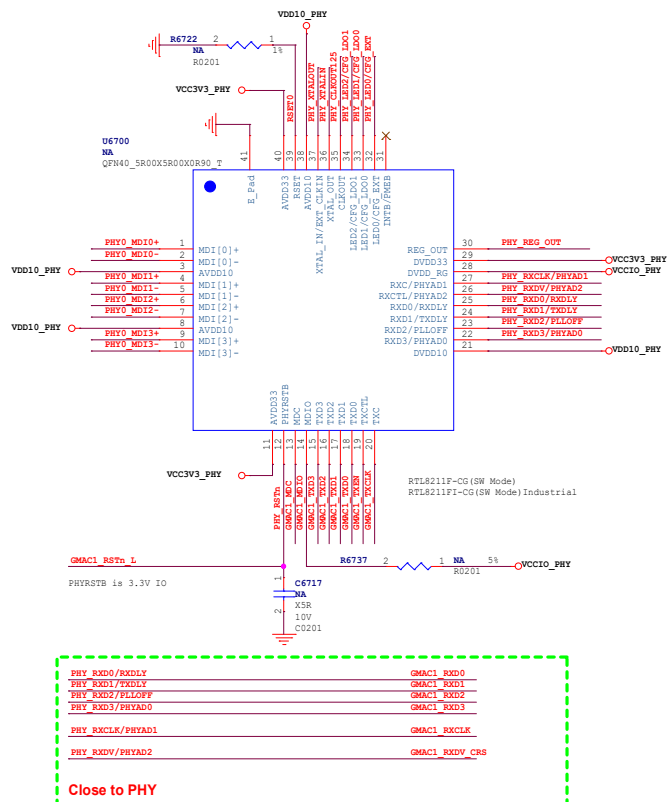
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Project:	RK3528_HT2	 HINLINK
File:	19.WIFI	
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RGMI I



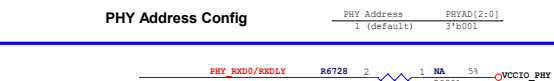
默认不带灯



VCC_PHY0_IO Voltage Config



PHY Address Config



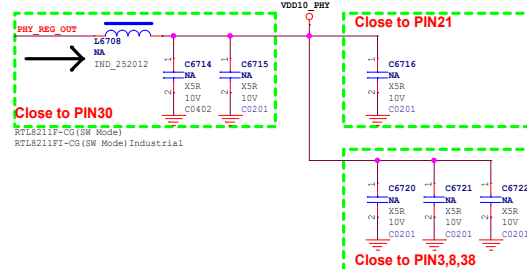
Pull-up for additional 2ns delay to RXC for data latching



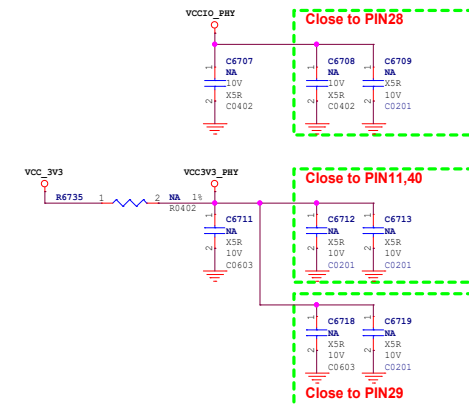
Pull-up for additional 2ns delay to TXC for data latching



Pull-up to disable PLL @ ALDPS mode(Low power mode)



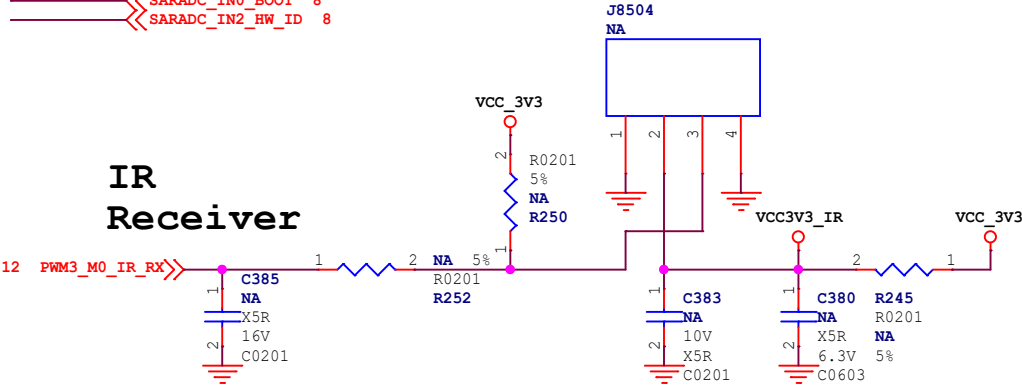
MMIO Power Source	CFG EXT	CFG LDO[1:0]
External 3.3V	1'b1	2'b00
External 1.8V	1'b1	2'b10
Internal 1.8V(default)	1'b0	2'b10



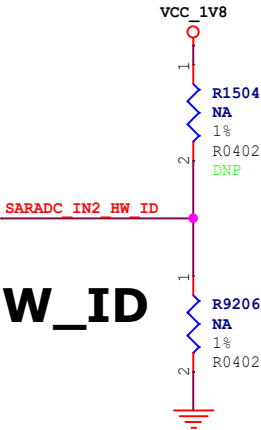
KEY

SARADC_IN0_BOOT 8
SARADC_IN2_HW_ID 8

IR Receiver



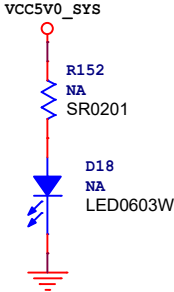
HW_ID



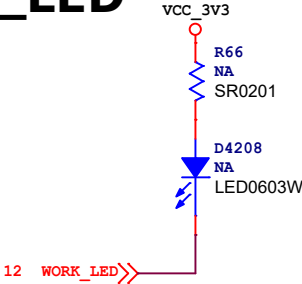
V1.0 TABLE

SARADC_IN2	Rup	Rdown	ADC
HW_ID0	DNP	100K	0
HW_ID1	100K	12K	114
HW_ID2	100K	27K	228
HW_ID3	100K	51K	342
HW_ID4	100K	82K	456
HW_ID5	100K	120K	570
HW_ID6	100K	200K	683
HW_ID7	100K	330K	796
HW_ID8	100K	820K	910
HW_ID9	100K	DNP	1023

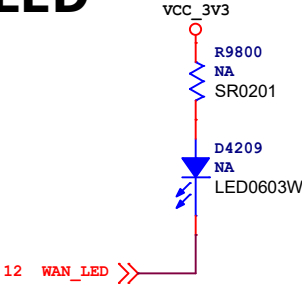
POWER_LED




WORK_LED



WAN_LED



HINLINK

Project:	RK3528_HT2	
File:	21.Key/HW ID/LED	
Date:	Monday, January 29, 2024	Rev: <Revision>
Designer:	<designer>	Sheet: 22 of 23

